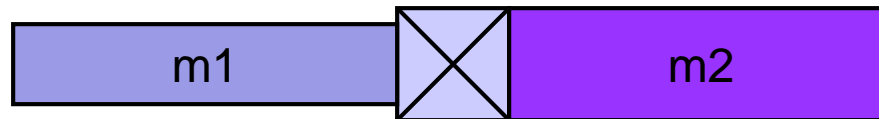


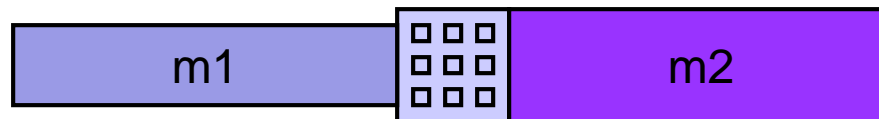
# PHOTOMASKS

# magic Layers vs. Mask Layers

- magic allows designers to work with logical layers
- Chip fabrication requires more detailed layers
- magic captures all necessary information and generates the rest
- Example magic layout with m1-m2 via



Example m1-m2 via pattern in actual mask



# Mask Costs

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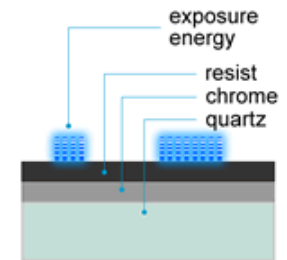
- Approximate cost for a set of masks for the indicated CMOS fabrication technology
  - 28 nm      \$2 million
  - 14/16 nm    \$4 million
  - 7 nm        \$8-10 million

[Mark Papermaster, CTO AMD, CTO Forum, Nov 2016]
- Two of the reasons for the dramatic increases in cost are the finer features sizes, and the need for many more masks for multiple patterning lithography

# How a Photomask is Made

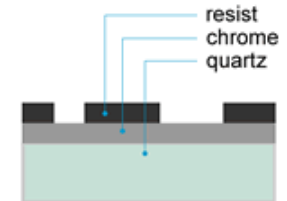
## 1. Generate Pattern

- Convert circuit design data to image in resist through e-beam/laser exposure.



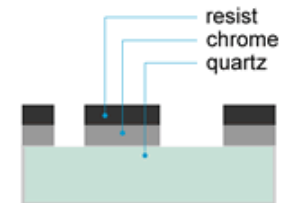
## 2. Develop Resist

- Develop temporary pattern in resist to serve as a match for etching.



## 3. Etch Chrome

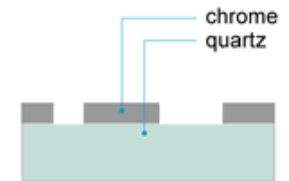
- Define permanent pattern in chrome.



# How a Photomask is Made

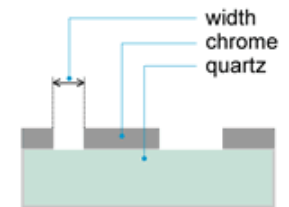
## 4. Remove Resist

- Remove temporary masking layer.



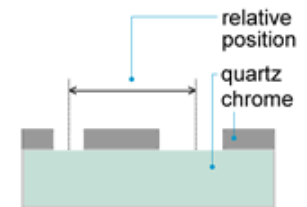
## 5. Measure Critical Dimensions

- Ensure features are the proper size.



## 6. Measure Feature Placement

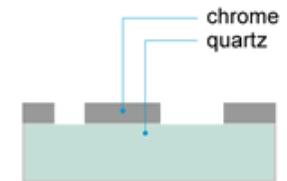
- Ensure features are in the proper position.



# How a Photomask is Made

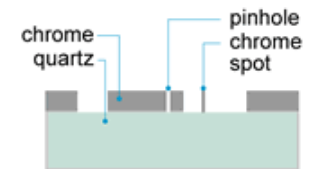
## 7. Initial Clean

- Clean for defect inspection.



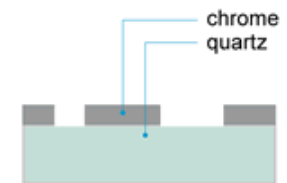
## 8. Inspect for Defects

- Ensure no unetched chrome or pinholes are present.



## 9. Repair

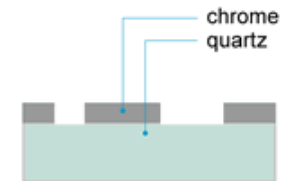
- Repair any defects found.



# How a Photomask is Made

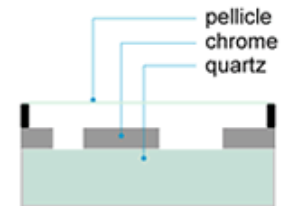
## 10. Pre-Pellicle Clean

- Remove any particulates before pellicle application.
- *Pellicle* is a protective cover that shields the photomask from damage and dirt.



## 11. Apply Pellicle

- Provide a particle barrier to ensure the integrity of the pattern from particles.



## 12. Audit

- Final check.

